Product Change Notification

Change Notification #: **115918 - 00**

Change Title: **Select Intel® SSD DC P4501 Series Products,**
PCN 115918-00, Product Design,
Change Bottom Enclosure Mylar

Date of Publication: **November 29, 2017**

Key Characteristics of the Change:

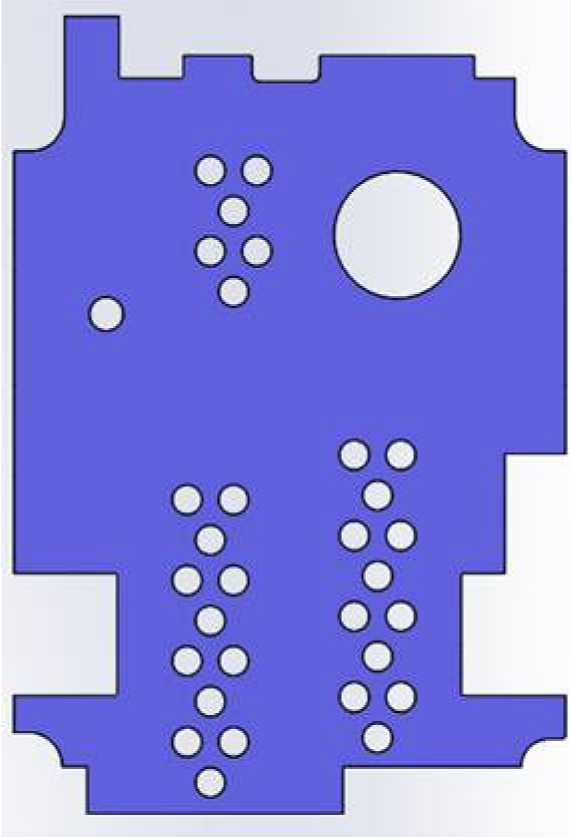
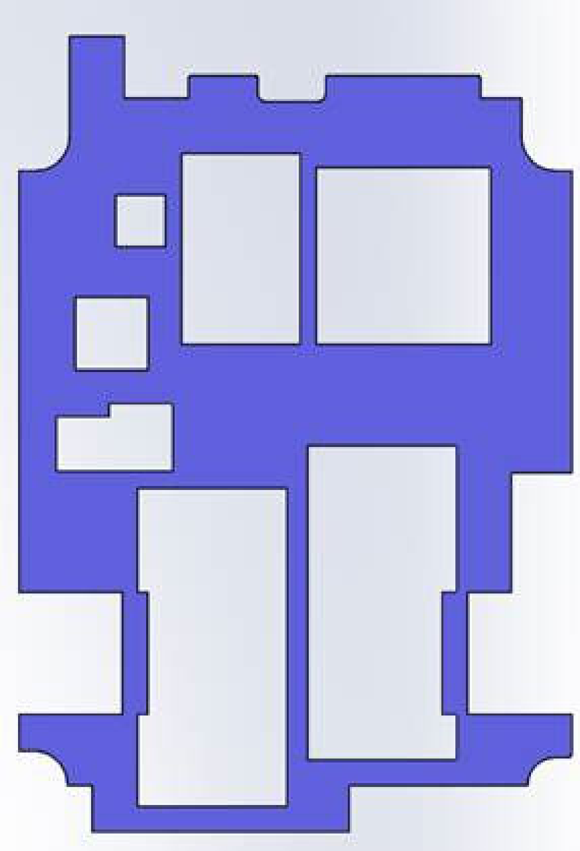
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	December 14, 2017

Description of Change to the Customer:

To improve thermal performance, Intel Corporation will be making a change to the bottom enclosure mylar as shown in the current and new images provided below:

Current	New
	

This design change dos not affect the form, fit, function, or performance of the Intel® SSD DC P4501 Series products listed on the "Products Affected/Intel Ordering Codes" table below.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers however, would like customers to be aware of the change.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#
Intel® SSD DC P4501 Series (500GB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic Single Pack	954762
Intel® SSD DC P4501 Series (1.0TB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic Single Pack	954764
Intel® SSD DC P4501 Series (2.0TB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic Single Pack	954766
Intel® SSD DC P4501 Series (4.0TB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic Single Pack	954980
Intel® SSD DC P4501 Series (500GB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic 50 Pack	957350
Intel® SSD DC P4501 Series (1.0TB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic 50 Pack	957351
Intel® SSD DC P4501 Series (2.0TB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic 50 Pack	957352
Intel® SSD DC P4501 Series (4.0TB, 2.5in PCIe 3.1 x4, 3D1, TLC) 7mm, Generic 50 Pack	957353

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
November 29, 2017	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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